3.4mm RIGHT ANGLE LED INDICATOR

Part Number: L-1384AD/1ID

High Efficiency Red

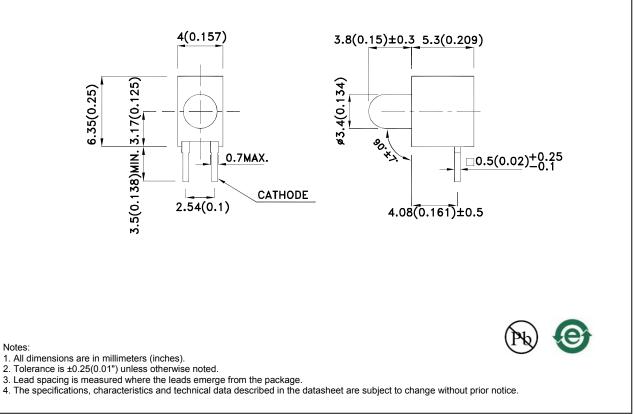
Features

- Ideal for card edge status indication.
- Wide viewing angle.
- High reliability-life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



SPEC NO: DSAB2488 APPROVED: WYNEC REV NO: V.14A CHECKED: Allen Liu DATE: APR/06/2013 DRAWN: Y.Liu

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Selection Guide lv (mcd) [2] Viewing @ 10mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. 12 25 L-1384AD/1ID High Efficiency Red (GaAsP/GaP) Red Diffused 60° *8 *16

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I⊧=20mA
С	Capacitance	High Efficiency Red	15		pF	V⊧=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I⊧=20mA
lr	Reverse Current	High Efficiency Red		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

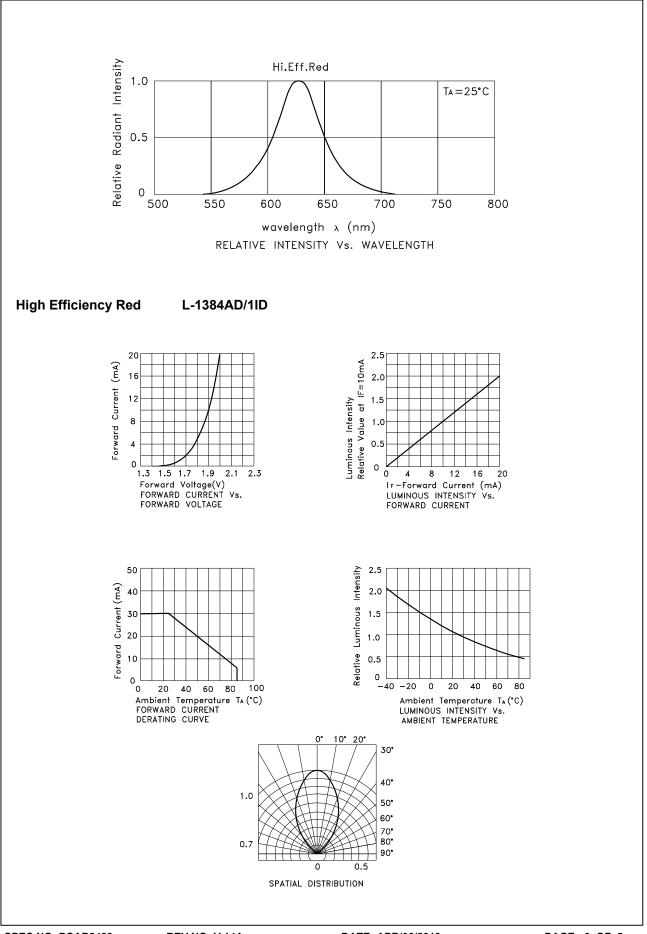
Absolute Maximum Ratings at TA=25°C

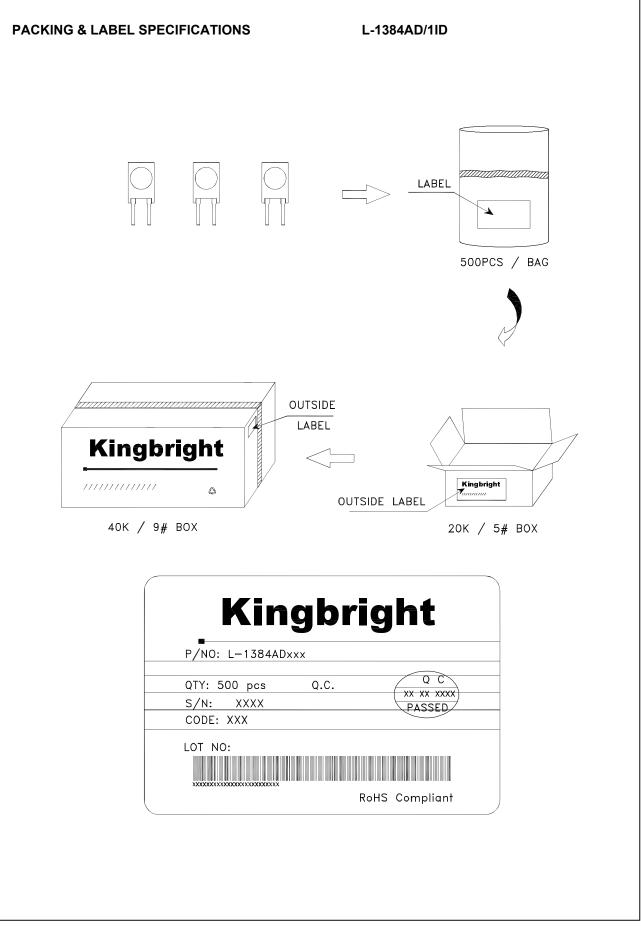
High Efficiency Red	Units				
75	mW				
30	mA				
160					
5	V				
-40°C To +85°C					
ead Solder Temperature [2] 260°C For 3 Seconds					
260°C For 5 Seconds					
	75 30 160 5 -40°C To +85°C 260°C For 3 Seconds				

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

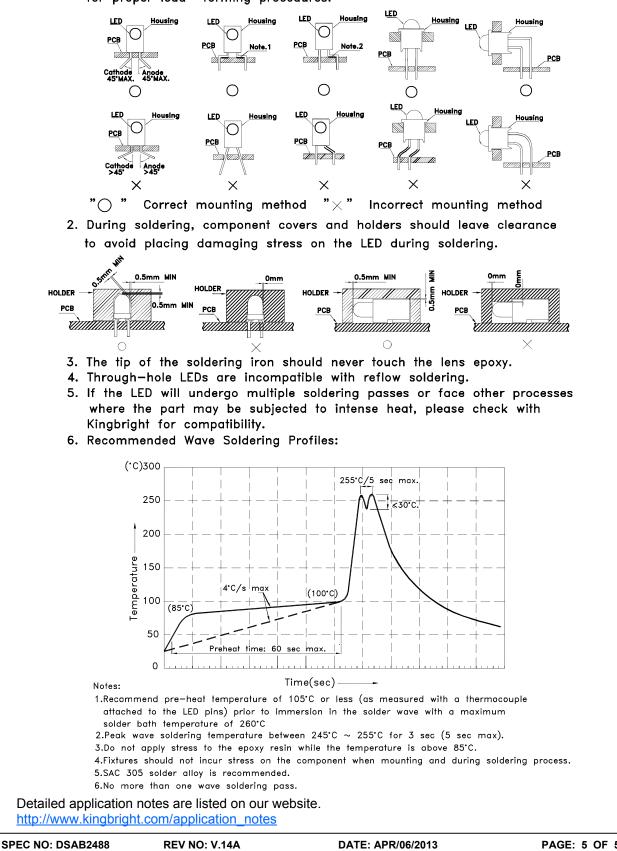
2. 2mm below package base.
3. 5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



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